

2018 FOA

COLLABORATIVE FORUM

Scottsdale, AZ | February 21-22



Connecting Manufacturing Challenges and Supply Chain Solutions



Agenda is subject to change

Wednesday – February 21, 2018

12:00 PM - 5:00 PM - Exhibit tables open

Device Makers Only Session

- 8:00 AM Registration Check-in & Gathering
- 8:30 AM Device Maker Meeting
- 12:00 PM DM Only Lunch - Sponsored by BISTel

General Meeting – Session #1

- 1:00 PM Registration Check-in
 - 1:30 PM **Welcome remarks** – Tom Salmon
 - 1:50 PM **Analyst Panel** – Lara Chamness, SEMI – Moderator
 - 2:35 PM **Case study #1 Tripling MTBC for Advanced RF application ICP SiN Etching - SPTS-Skyworks**
 - 3:05 PM **Case study #2 Using FabGuard to improve LAM Rainbow TCP tools - Inficon-TowerJazz Israel**
 - 3:35 PM Break - Sponsored by Semplastics
 - 3:55 PM **Smart Data + Other** – Dave Anderson, SEMI Amereicas
 - 4:25 PM Evening Social Sponsor presentation (TBD)
 - 4:45 PM **Case study #3 Eagleview imager upgrade for better defect detection - Microtronic-X-FAB**
 - 5:15 PM **Day 1 Wrap-up**
 - 6:30-9PM *Evening Social at Musical Instrument Museum
4725 E Mayo Blvd, Phoenix, AZ 85050*
- Transportation will NOT be provided

Thursday – February 22, 2018

8:30 AM - 5:30 PM - Exhibit tables open

General Meeting – Session #2

- 8:00 AM Registration Check-in & Gathering
- 8:30 AM Welcome remarks –Tom Salmon
- 8:45 AM **Case Study #4 Replacement of Isopropyl Alcohol for VOC free cleaner - Keteca-Skyworks**
- 9:15 AM **Case study #5 Achieving consistent high yield in a fab through Chamber Matching - BISTel-Qorvo**
- 9:45 AM **Invited Speaker** (TBD)
- 10:15 AM Break
- 10:45 AM **Case study #6 Increase in exhaust line maintenance interval using low cost nitrogen inject - Sparetech-X-FAB**
- 11:15 AM **Group Purchasing Organization Update – Darryl Buck, GPS/SEMI**
- 11:45 AM **Invited Speaker** (TBD)
- 12:15 PM Lunch Sponsor presentation - INFICON
- 12:25 PM Lunch - Sponsored by INFICON

General Meeting – Session #3

- 2:00 PM **Emerging Issues in Automotive Product Liability Cases: Electronic/Software Defects – Exponent, Inc.**
- 2:30 PM Post-Forum Sponsor presentation – OEM Group
- 2:40 PM **Case study #7 Slurry Flow Reduction for BEOL CMP - Semplastics-Microchip**
- 3:10 PM Break
- 3:40 PM **Case study #8 Dry Vacuum pump replacement project - Ebara-Qorvo**
- 4:10 PM **Invited Speaker** (TBD)
- 4:40 PM Wrap-up & feedback
- 6-8:00PM *Post-Forum reception at DoubleTree Resort - Sponsored by OEM Group*